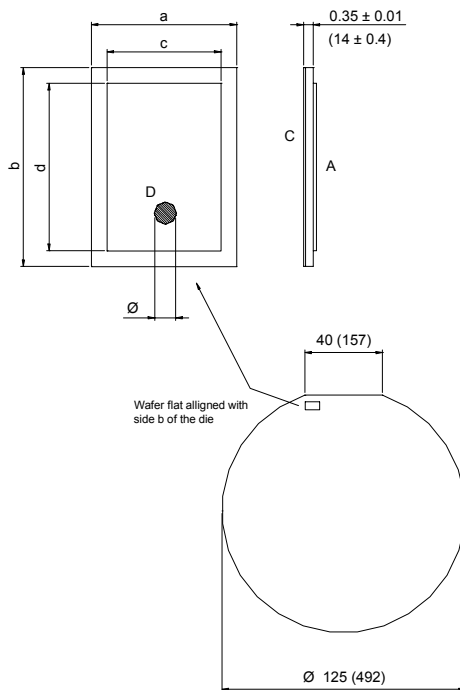


International
IOR Rectifier

SC021....5. Series

SCHOTTKY DIE 21 x 45 mils



NOTES:

1. ALL DIMENSIONS ARE SHOWN IN MILLIMETERS (MILS).
2. CONTROLLING DIMENSION: (MILS).
3. DIMENSIONS AND TOLERANCES:
 $a = 0.53 \pm 0.01$
 (21 $\pm$ 0.4)
 $b = 1.14 \pm 0.01$
 (45 $\pm$ 0.4)
 $c = 0.38 \pm 0.01$
 (15 $\pm$ 0.4)
 $d = 0.99 \pm 0.01$
 (39 $\pm$ 0.4)
 $\varnothing = 0.4 \pm 0.1$
 (15 $\pm$ 4)
4. LETTER DESIGNATION:
 A = Anode (Top Metal)
 C = Cathode (Back Metal)
 D = Reject Ink Dot (only on non-conforming dies)
 (Sample Probe)
5. SAWING:
 Recommended Blade
 SEMITEC S1025 QS00 Blade
 Sawing Street
 0.05 ± 0.005
 (2 $\pm$ 0.2)

NOT TO SCALE

NOTE: 10 mils die thickness is available on specific request only.
Contact factory for information.

Electrical Characteristics

Device #	T _J Max. (°C)	V _R (V)	Typ. I _R @ 25°C (μA)	Typ. I _R @ 125°C (mA)	Max. V _F @ I _F (V)	Package Style
SC021 R 015x5x	125	15	n.a. contact factory			
SC021 S 020x5x	150	20	n.a. contact factory			
SC021 S 030x5x	150	30	n.a. contact factory			
SC021 S 045x5x	150	45	n.a. contact factory			
SC021 S 060x5x	150	60	n.a. contact factory			
SC021 H 045x5x	175	45	n.a. contact factory			
SC021 H 100x5x	175	100	n.a. contact factory			
SC021 H 150x5x	175	150	n.a. contact factory			

Mechanical Data

Device #		Metal Thickness Front Metal			Metal Thickness Back Metal		
SC021xxxx A 5x	Bondable	–	Al/Si 30 kÅ	–	Cr 1 kÅ	Ni 2 kÅ	Ag 3 kÅ
SC021xxxx S 5x	Solderable	Ti 2 kÅ	Ni 1 kÅ	Ag 35 kÅ	Cr 1 kÅ	Ni 2 kÅ	Ag 3 kÅ

Recommended Storage Environment: Store in original container, in dessicated nitrogen, with no contamination.

Shelf life for parts stored in above condition is 2 years.

If the storage is done in normal atmosphere shelf life is reduced to six months.

Packaging

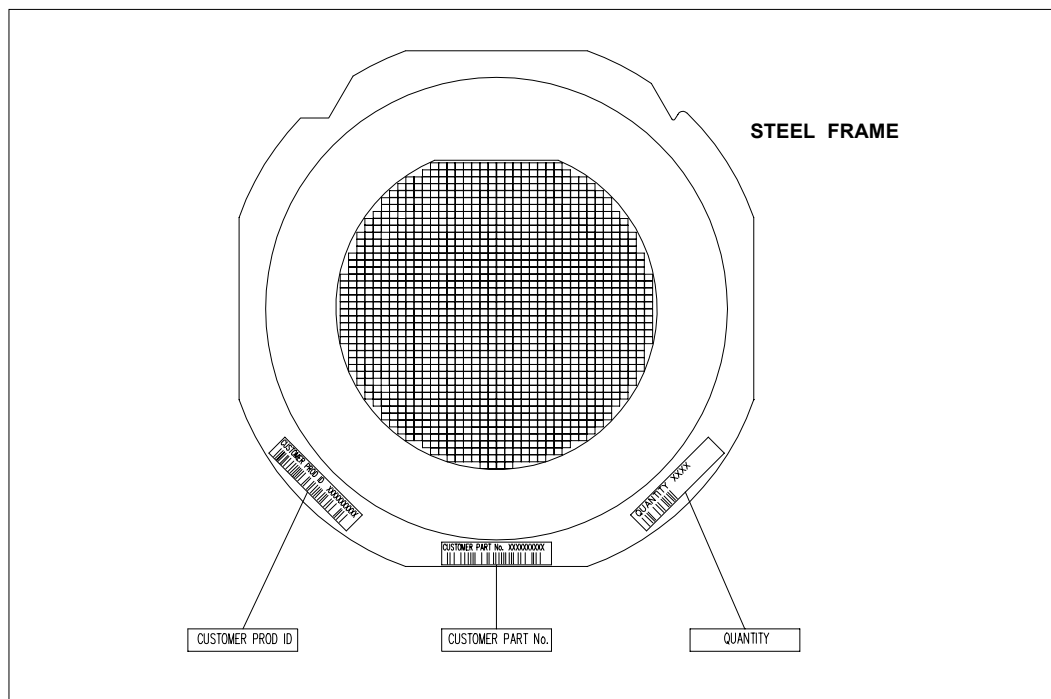
Device #	Description	Minimum Order Quantity Die in Sale Package
SC021xxxx B	Inked Probed Unsawn Wafer (Wafer in Box)	17500
SC021xxxx R	Probed Die in Tape & Reel	n.a.
SC021xxxx P	Probed Die in Waffle Pack	n.a.
SC021xxxx F	Inked Probed Sawn Wafer on Film	17500

Ordering Information Table

Device Code						
1	2	3	4	5	6	7
SC	021	S	030	S	5	B
1	- Schottky Die					
2	- Chip Dimension in Mils					
3	- Process (see Electrical Characteristics Table)					
4	- Voltage code: Code = V_{RRM}					
5	- Chip surface metallization (see Mechanical Data Table)					
6	- Wafer Diameter in inches					
7	- Packaging (see Packaging Table)					

H = 830 Process
R = OR'ing Process
S = Standard Process

Wafer on Film

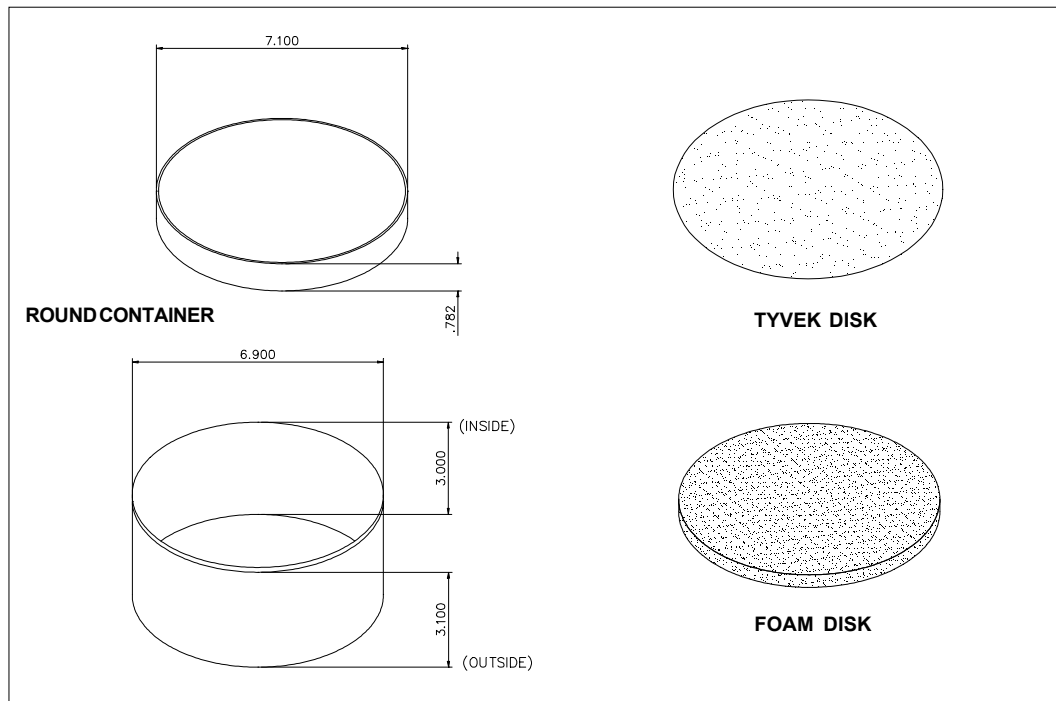


SC021.....5. Series

Bulletin I0405J rev. A 05/01

International
IOR Rectifier

Wafer in Box



International
IOR Rectifier

IR WORLD HEADQUARTERS: 233 Kansas St., El Segundo, California 90245, USA Tel: (310) 252-7105
TAC Fax: (310) 252-7309
Visit us at www.irf.com for sales contact information. 03/01